NEW

0.35mm Pitch, 2.0mm Depth, 0.6mm Stacking Height Multi-RF Compatible Board-to-Board Connector

BM46 Series



Features

- 1. Multi-RF capable Board-to-Board connector, World's smallest width class Pitch : 0.35mm, Width : 2.0mm, Stacking height : 0.6mm
- 2. Contact design ideal for both high speed digital transmission and RF signal
- 3. Superior RF Signal Transmission V.S.W.R. 0-3GHz : 1.3 Max. 3-6GHz : 1.4 Max.

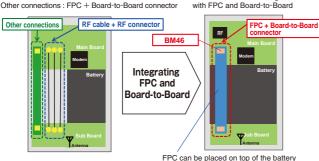
6-12GHz : 1.6 Max.

- 4. Center shield prevents signal noise between opposing rows
- 5. Robust metal mating guides

Applications

Thin devices such as cell phones, tablet PCs, routers, etc. that require spacesaving components.

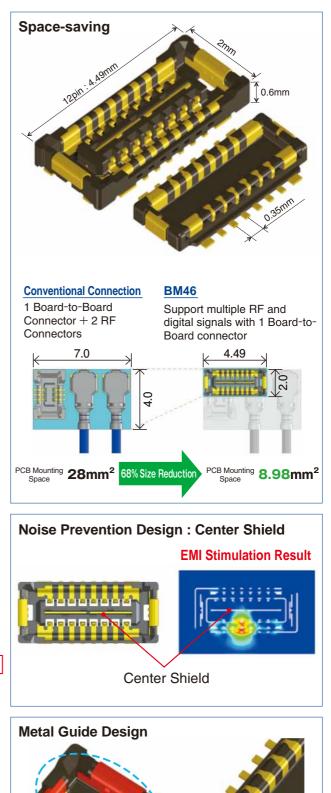
Conventional Internal Connection RF connection : RF cable + RF connector Other connections : FPC + Board-to-Board connector



Environmental

Halogen-free*

In accordance with IEC 61249-2-21 Br : 900ppm max, CI : 900ppm max Br+CI : 1500ppm max



In cases where the application will demand a high level of reliability, such as automotive, please contact a company representative for further information.

New Proposed Design

Connect RF and other signals

2019.11 **HS** 1

Product Specifications

| Product Speci | icalio | 115 | | | | |
|------------------------------|------------|--|---|---|--|--|
| Rated Current : Signal Conta | act : 0.3A | Operating Temperature : -55 to +85°C (Note 1) | | Storage Temperature Range : -55 to +60°C | | |
| Rated Voltage 30V AC/DC | | | | Operating Humidity Range : 90% RH Max. (Note 2, 3) | | |
| Characteristic Impedance : 5 | 60Ω | Rated Frequency : DC to 12 GHz | 2 | | | |
| Item | | Specifications | Conditions | | | |
| 1. Contact Resistance | Signal C | ontact 100mΩ Max. | Measured | d at 20mV AC, 1kHz, and 1mA | | |
| 2. Insulation Resistance | 100MΩ Ν | Min. | Measured | Measured at 100V DC | | |
| 3. Withstanding Voltage | No flashe | over or dielectric breakdown | 150V AC for 1 minute | | | |
| 4. Mating Durability | Signal C | ontact 100mΩ Max. | 10 Mating Cycles | | | |
| 5. Vibration | No electi | rical discontinuity of 1μ s or more. | Frequency : 10 to 55Hz ; half amplitude of 0.75mm,10 cycles in each of 3 axis directions for 5 minutes/cycle, 30 cycles total | | | |
| 6. Shock Resistance | No electi | rical discontinuity of 1μ s or more. | Acceleration : 450m/s ² , duration : 11ms, 3-axis half sine wave in both directions, 3 cycles for each | | | |
| 7. Humidity | - | ontact : 100m Ω Max. n Resistance : 50m Ω | Left for 96 hours at a temperature of 40 $\pm 2^\circ C$ and a humidity range from 90 to 95% | | | |
| 8. Temperature Cycle | 0 | ontact : 100m Ω Max. n Resistance : 100m Ω Min. | -55±3°C : 30 minutes → 85±2°C : 30 minutes, 5 cycles | | | |
| 9. Solder Heat Resistance | | lution or melting of the resin that t performance. | t Reflow : with recommended temperature profile Hand soldering at soldering iron temperature of 350°C for 3 seconds max. | | | |
| | | | | | | |

Note 1 : Includes temperature rise caused by current flow.

1.3 Max.

1.4 Max.

1.6 Max.

Note 2 : Storage refers to long-term-storage of unused items before they are mounted on the PCB.

Operating temperature and humidity range apply when the product is not powered after PCB mounting and when temporarily stored during transportation.

0-3GHz

3-6GHz

6-12GHz

Note 3 : Use without condensation.

10. V.S.W.R.

Materials/ Finish

| Product | Part | Materials | Finish | UL Regulation |
|---------------------|-----------|-----------------|-------------|---------------|
| Hander / Decentaria | Insulator | LCP | Black | UL94V-0 |
| Header / Receptacle | Contact | Phosphor Bronze | Gold Plated | _ |

Product Number Structure

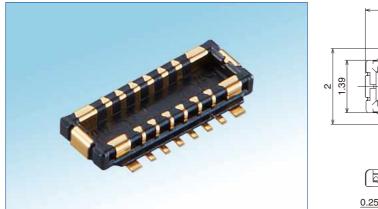
Refer to the chart below when determining the product specifications from the product number. Please select from the product numbers listed in this catalog when placing orders.

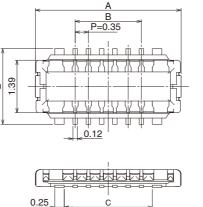
Header / Receptacle

| <u>BM46</u> B - | * | DP | - 0.35 | V | (**) |
|-----------------|---|----|--------|---|------|
| 1 | - | 3 | 4 | _ | _ |

| Series Name | : BM46 | | | | | |
|---|-----------------------------|--|--|--|--|--|
| 2No. of Signal Contacts : 12 | | | | | | |
| Onnector Type | DP : Header DS : Receptacle | | | | | |
| 4Contact Pitch | : 0.35mm | | | | | |
| 5 Termination Type | : Straight SMT | | | | | |
| Gold plating and packaging conditions (51) : Gold plating Embossed tape packaging (20,000 pcs/reel) (53) : Gold plating | | | | | | |
| Embossed tape packaging (1,000 pcs/reel) | | | | | | |

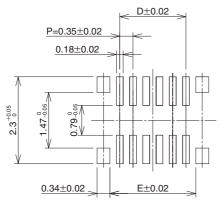
Header



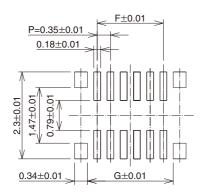




Recommended PCB Layout



■Recommended Metal Mask Dimensions (Mask Thickness : 80µm)



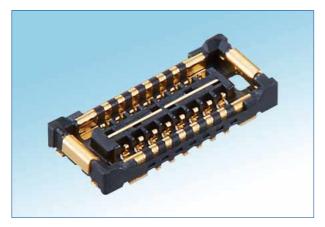
| Part No. | HRS No. | No. of contacts | А | В | С | D | E | F | G |
|----------------------|---------------|-----------------|------|------|------|------|------|------|------|
| BM46B-12DP-0.35V(**) | 673-7055-0 ** | 12 | 3.85 | 1.75 | 2.33 | 1.75 | 2.27 | 1.75 | 2.27 |

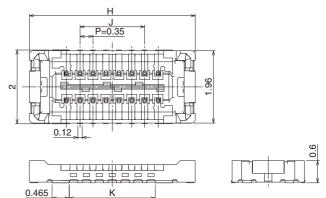
Note 1 : Please place orders in full reel quantities.

Note 2 : This connector has no polarity.

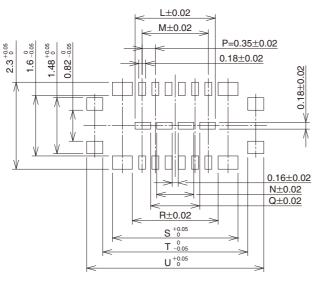


Receptacle

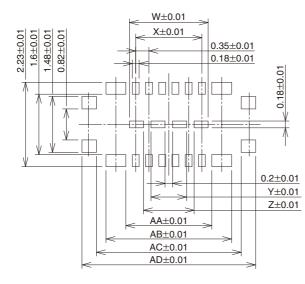




Recommended PCB Layout



■Recommended Metal Mask Dimensions (Mask Thickness : 80µm)

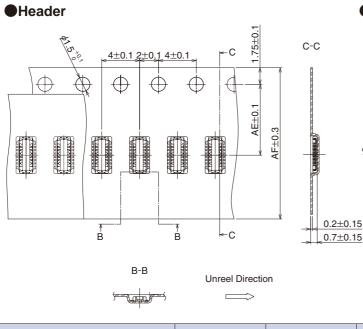


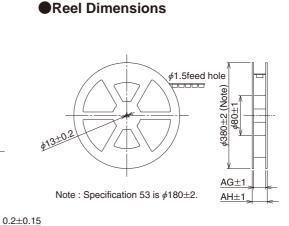
| Part No. | HRS No. | No. of contacts | Н | J | К | L | М | N | Q | R | S | Т |
|----------------------|---------------|-----------------|------|------|------|------|------|------|------|------|------|------|
| | | | 4.49 | 1.75 | 2.33 | 2.12 | 1.75 | 0.98 | 1.3 | 2.27 | 3.32 | 3.83 |
| BM46B-12DS-0.35V(**) | 673-7054-0 ** | 12 | U | W | Х | Y | Z | AA | AB | AC | AD | |
| | | | 4.68 | 2.08 | 1.75 | 0.94 | 1.34 | 2.27 | 3.32 | 3.83 | 4.59 | |

Note 1 : Please place orders in full reel quantities. Note 2 : This connector has no polarity.



Embossed Tape Dimensions (IEC 60286-3, JIS C 0806)





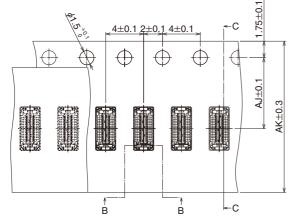
| Part No. | No. of Contacts | AE | AF | AG | AH |
|----------------------|-----------------|-----|----|------|------|
| BM46B-12DP-0.35V(**) | 12 | 7.5 | 16 | 17.4 | 21.4 |

C-C

Embossed Tape Dimensions (IEC 60286-3, JIS C 0806)

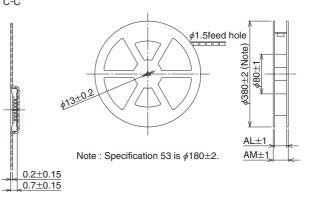
Receptacle

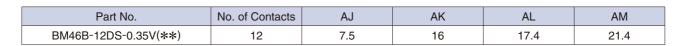




B-B Just in the second second

Unreel Direction \Longrightarrow





♦ Precautions

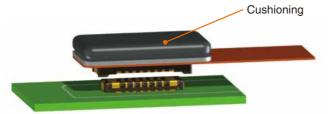
| 1 Decommonded Solder | | | | | | | |
|---|--|--|--|--|--|--|--|
| 1. Recommended Solder Temperature Profile | Temperature (°C) | | | | | | |
| remperature i rome | MIAZ200 | | | | | | |
| | 250 | | | | | | |
| | 220 = | | | | | | |
| | 180 <u>180°C</u> | | | | | | |
| | 150 | | | | | | |
| | 150°C | | | | | | |
| | | | | | | | |
| | | | | | | | |
| | | | | | | | |
| | | | | | | | |
| | | | | | | | |
| | (60 sec.) 90-120sec. MAX 60 sec. | | | | | | |
| | (150 to 180°C) (220°C Min.) | | | | | | |
| | [Conditions] | | | | | | |
| | 1. Peak temperature : Maximum of 250°C | | | | | | |
| | 2. Heating : 220°C min., within 60 sec | | | | | | |
| | 3. Preheating : 150 to 180°C, 90 to 120 sec | | | | | | |
| | 4. Number of Reflow Cycles : Maximum of 2 cycles | | | | | | |
| | Note 1 - The temperature refers to the surface temperature of the DCP near the connector | | | | | | |
| | Note 1 : The temperature refers to the surface temperature of the PCB near the connector lead. | | | | | | |
| | Note 2 : When using nitrogen reflow, oxygen concentration must be 1000 [ppm] or more for | | | | | | |
| | mounting. If it is less than 1000 [ppm], please contact a Hirose representative. | | | | | | |
| | Soldering iron temperature : $340 \pm 10^{\circ}$ C : | | | | | | |
| 2. Recommended Manual Soldering Conditions | Soldering iron temperature : $340 \pm 10^{\circ}$ C ; | | | | | | |
| 0 | Soldering time : within 3 seconds | | | | | | |
| 3. Recommended Stencil Thickness and Open Area | Thickness : 0.08mm | | | | | | |
| to PCB Pattern Area Ratio | Aperture Ratio : Receptacle Side : 100%, Header Side:100% | | | | | | |
| 4. Board Warpage | A maximum of 0.02mm at the center of the connector relative to each end of the connector. | | | | | | |
| | Cleaning is not recommended. If you clean this product, please evaluate its performance | | | | | | |
| | before using it. | | | | | | |
| 5. Cleaning Conditions | - | | | | | | |
| | (Cleaning may impair the mating/unmating properties and lower resistance to environmental factors) | | | | | | |
| | | | | | | | |
| 6. Precautions | Care should be taken when mating/unmating the connector when it is not mounted on the | | | | | | |
| | PCB as it may cause damage/ deformation to contacts. | | | | | | |
| | Avoid supporting the PCB only with the connectors. | | | | | | |
| | Support it by other means such as bolts, screws, posts, etc. | | | | | | |
| | Excessive prying during unmating/mating may result in damage. | | | | | | |
| | In the case of hand soldering, please do not apply any flux which could cause flux wicking. | | | | | | |
| | This product may have slight color differences due to production lot variability, but this | | | | | | |
| | does not affect the performance. | | | | | | |
| | Please refer to the following page for handling precautions when inserting and removing. | | | | | | |
| | Because the product can disengage if dropped (or other impact), or by FPC routing, it is | | | | | | |
| | advised to secure the mated connectors to the board with housings and cushioning | | | | | | |
| | materials. | | | | | | |
| | Do not use the connector in non-recommended conditions (i.e., rated current, rated | | | | | | |
| | voltage, PCB design and operating environment, etc.). Such usage could lead to | | | | | | |
| | material outgassing, ignition, or short-circuit, etc. | | | | | | |
| | Refer to the specifications and guidelines for board pattern dimensions, board cautions, | | | | | | |
| | and connector treatment. | | | | | | |
| | Please contact Hirose if connector usage in conditions other than those described in the | | | | | | |
| | specifications and the guidelines is being considered. | | | | | | |

Connector Handling Precautions

Disengagement Prevention

Please use cushioning

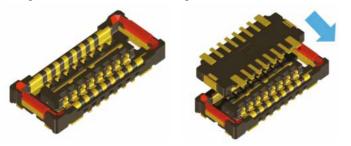
The connector may come off due to impact such as dropping. Cushioning should be large enough to cover the entire connector.



Mating Method

1) Locate the guide port and align.

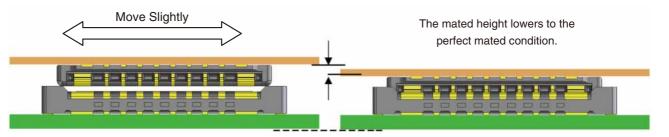
This product has a guide rib on the receptacle side to ensure proper engagement. Align the connector based on the guide rib.



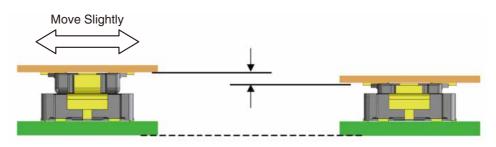
2)Once aligned, the connector engages.

You can feel the mated height of the connector lower.

Move the connector forward and backward, left and right to find the guide port.



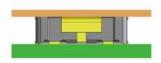
3)In the engaged state, the connectors are parallel to each other, and the connectors cannot move forward, backward, left, or right. Complete mating from this state.



4) Check that mating is completed.

If one side is floating, or if it is mated diagonally, remove and re-mate.



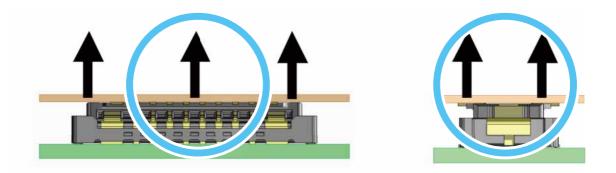




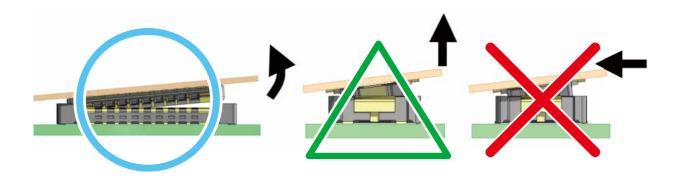
Handling Precautions for Connector Removal

1) When removing the connector, it is preferable to pull it out in the upward direction from the connector mounting surface.

However when removing the FPC from the circuit board it becomes more difficult to remove it vertically with higher pin counts and thin FPCs.



2) If difficult to remove, extract the connector diagonally in the direction of the pitch.
Note that removal from the widthwise side will apply a large load to the contacts. When removing from the width direction, pull the end of the FPC in the upward direction.
(When a force is applied in the horizontal direction, a large load is applied to the contact.)



3) If the FPC does not have sufficient rigidity, solder stripping or connector breakage may occur. Please use it after checking the repetitive operation with the flexible board you during a trial manufacture run. Refrain from holding the corner of the flexible board and removing it diagonally as it will result in a large load to the contacts.



The characteristics and the specifications contained herein are for reference purpose. Please refer to the latest customer drawings prior to use. The contents of this catalog are current as of date of 11/2019. Contents are subject to change without notice for the purpose of improvements.

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Hirose Electric: BM46B-12DS-0.35V(53) BM46B-12DP-0.35V(53)